



## Product Change Notification: NTDO-11USUI436

### Date:

12-Feb-2025

### Product Category:

32-Bit Microcontrollers

### Notification Subject:

CCB 7412 Initial Notice: Qualification of palladium-coated copper with gold flash (CuPdAu) as a new wire material for ATSAM4LS2CA, ATSAM4LC8CA, ATSAM4LS8CA, AT32UC3A1512, AT32UC3A1128, AT32UC3A1256, ATSAM4LC4CA, ATSAM4LS4CA, ATSAM4LC2CA, AT32UC3C1128C, AT32UC3C1256C, AT32UC3C1512C and AT32UC3C164C device families available in 100L TQFP (14x14x1mm) package assembled at MMT assembly site.

### Affected CPNs:

[\*\*NTDO-11USUI436\\_Affected\\_CPN\\_02122025.pdf\*\*](#)  
[\*\*NTDO-11USUI436\\_Affected\\_CPN\\_02122025.csv\*\*](#)

**PCN Status:** Initial Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of palladium-coated copper with gold flash (CuPdAu) as a new wire material for ATSAM4LS2CA, ATSAM4LC8CA, ATSAM4LS8CA, AT32UC3A1512, AT32UC3A1128, AT32UC3A1256, ATSAM4LC4CA, ATSAM4LS4CA, ATSAM4LC2CA, AT32UC3C1128C, AT32UC3C1256C, AT32UC3C1512C and AT32UC3C164C device families available in 100L TQFP (14x14x1mm) package assembled at MMT assembly site.

### Pre and Post Summary Changes:

	Pre Change	Post Change

<b>Assembly Site</b>	Microchip Technology Thailand (MMT)	Microchip Technology Thailand (MMT)
<b>Wire Material</b>	Au	CuPdAu
<b>Die Attach Material</b>	3280	3280
<b>Molding Compound Material</b>	G700HA	G700HA
<b>Lead-Frame Material</b>	C7025	C7025
<b>Lead-Frame Design</b>	See pre and post change summary for comparison	

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve manufacturability by qualifying CuPdAu as a new wire material.

**Change Implementation Status:** In Progress

**Estimated Qualification Completion Date:** March 2025

**Note:** Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Timetable Summary:**

	February 2025					March 2025				
Work Week	05	06	07	08	09	10	11	12	13	14
Initial PCN Issue Date			X							

<b>Qual Report Availability</b>									X	
<b>Final PCN Issue Date</b>									X	

**Method to Identify Change:** Traceability Code

**Qualification Plan:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:** February 12, 2025: Issued initial notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

### Attachments:

[\*\*PCN\\_NTDO-11USUI436\\_Qual\\_Plan.pdf\*\*](#)

[\*\*PCN\\_NTDO-11USUI436\\_Pre and Post\\_Change\\_Summary.pdf\*\*](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

### Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.